



P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
00)/	$80m\Omega @ V_{GS} = -4.5V$	-3.5A
-20V	$110m\Omega$ @ $V_{GS} = -2.5V$	-3.0A

Description

This MOSFET is designed to minimize the on-state resistance $(R_{DS(ON)})$ yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

- Backlighting
- Power Management Functions
- DC-DC Converters
- Motor Control

Features

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMP2110UQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

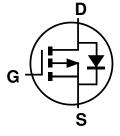
https://www.diodes.com/quality/product-definitions/

Mechanical Data

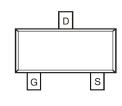
- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound;
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (§3)
- Terminals Connections: See Diagram Below
- Weight: 0.008 grams (Approximate)







Internal Schematic



Top View Pin Configuration

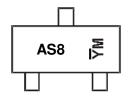
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2110UQ-7	SOT23	3,000/Tape & Reel
DMP2110UQ-13	SOT23	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



 $\begin{array}{l} AS8 = Product\ Type\ Marking\ Code \\ \underline{Y}M = Date\ Code\ Marking \\ Y = Last\ Digit\ of\ Year\ (ex:\ H=2020) \\ M = Month\ (ex:\ 9 = September) \end{array}$

Date Code Key

Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	Н	ı	J	K	L	М	N	0	Р	R	S	T
	1	1	1									
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage		V_{DSS}	-20	V	
Gate-Source Voltage		Vgss	±10	V	
Continuous Drain Current (Note 6) $V_{GS} = -4.5V$ Steady $T_A = +25^{\circ}C$ State $T_A = +70^{\circ}C$			lo	-3.5 -2.8	Α
Continuous Drain Current (Note 6) $V_{GS} = -2.5V$ Steady $T_A = +25^{\circ}C$ State $T_A = +70^{\circ}C$			lo	-3.0 -2.4	Α
Maximum Continuous Body Diode Forward Curre	ent (Note 6)	Is	-1.5	Α	
Pulsed Drain Current (10µs Pulse, Duty Cycle =	1%)		I _{DM}	-15	Α

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		PD	0.8	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Reja	158	°C/W
Total Power Dissipation (Note 6)		PD	1.2	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Reja	100	°C/W
Operating and Storage Temperature Range	<u>.</u>	TJ, TSTG	-55 to +150	°C

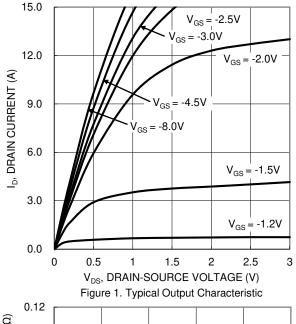
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

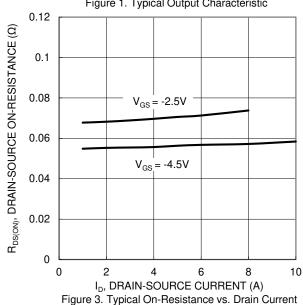
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_		٧	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	IDSS		_	-1.0	μΑ	V _{DS} = -16V, V _{GS} = 0V
Gate-Source Leakage	Igss		_	±100	nA	$V_{GS} = \pm 8V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	-0.45	_	-1.0	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$
Static Drain-Source On-Resistance			55	80	mΩ	$V_{GS} = -4.5V$, $I_D = -2.8A$
Static Drain-Source On-Resistance	RDS(ON)		67	110	11177	Vgs = -2.5V, ID = -2.0A
Diode Forward Voltage	V _{SD}		-0.7	-1.0	V	V _G S = 0V, I _S = -1A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss		443		рF	10)/)/
Output Capacitance	Coss		59		рF	V _{DS} = -10V, V _{GS} = 0V -f = 1.0MHz
Reverse Transfer Capacitance	Crss		47	_	рF	1 = 1.0ivinz
Gate Resistance	Rg		8.5	_	Ω	$V_{GS} = 0V$, $V_{DS} = 0V$, $f = 1.0MHz$
Total Gate Charge	Qg		6.0		nC	
Gate-Source Charge	Qgs		0.6	_	nC	$V_{GS} = -4.5V$, $V_{DS} = -10V$, $I_{D} = -3A$
Gate-Drain Charge	Qgd		1.8	_	nC	1
Turn-On Delay Time	tD(ON)		4.0	_	ns	
Turn-On Rise Time	t _R		3.7	_	ns	$V_{DS} = -10V, V_{GS} = -4.5V,$
Turn-Off Delay Time	tD(OFF)	_	24.5	_	ns	$R_L = 10\Omega$, $R_G = 1.0\Omega$, $I_D = -1A$
Turn-Off Fall Time	tF		9.5	_	ns	1
Reverse Recovery Time	t _{RR}	_	8.3	_	ns	I _F = -1.0A, di/dt = 100A/μs
Reverse Recovery Charge	Qrr		2.0	_	nC	I _F = -1.0A, di/dt = 100A/μs

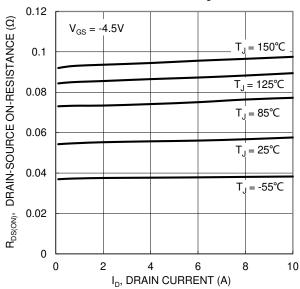
 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing. Notes:





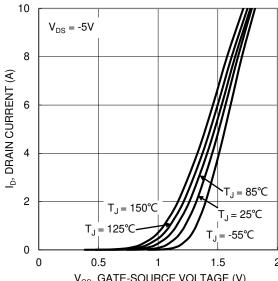




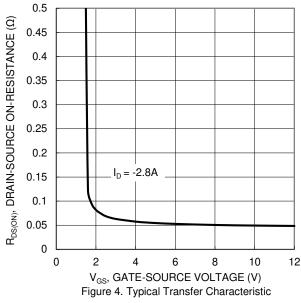


and Gate Voltage

Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature



 ${
m V_{GS}},~{
m GATE}\mbox{-}{
m SOURCE}~{
m VOLTAGE}~({
m V})$ Figure 2. Typical Transfer Characteristic



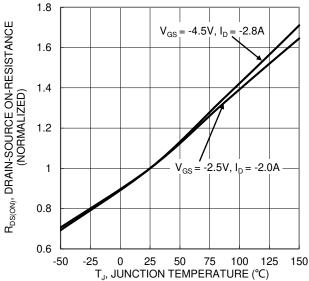


Figure 6. On-Resistance Variation with Junction Temperature





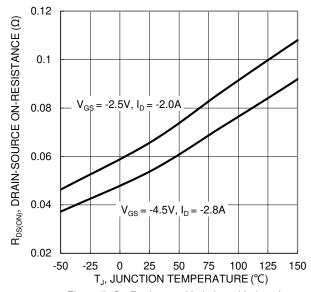
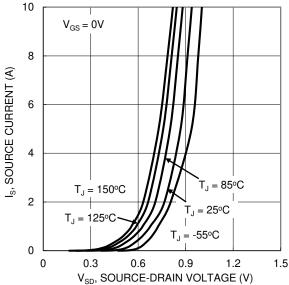
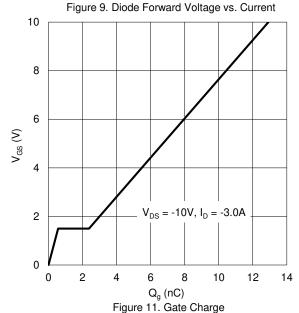


Figure 7. On-Resistance Variation with Junction Temperature





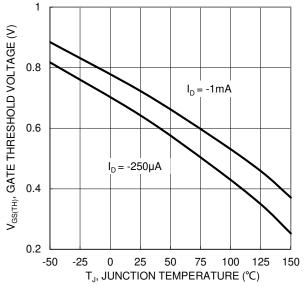
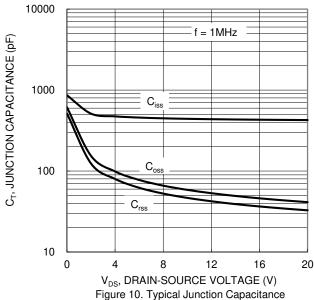


Figure 8. Gate Threshold Variation vs. Junction Temperature



100 R_{DS(ON)} Limited 100µs 10 ID, DRAIN CURRENT (A) $P_W = 100 ms$ T_{J(Max)} = 150℃ $T_C = 25^{\circ}C$ 0.1 Single Pulse DUT on 1*MRP Board $P_W = 10s$ DC $V_{GS} = -4.5V$ 0.01 0.1 10 100 V_{DS} , DRAIN-SOURCE VOLTAGE (V)

Figure 12. SOA, Safe Operation Area



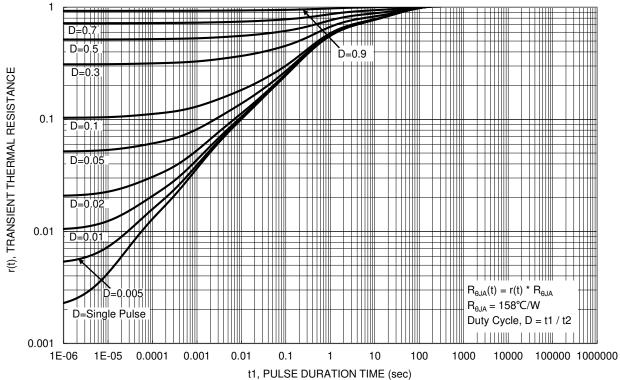


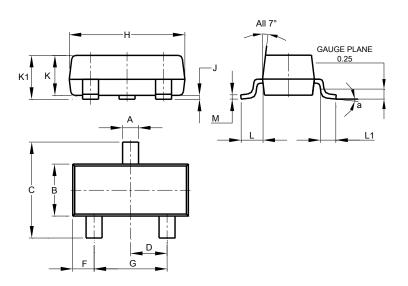
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23

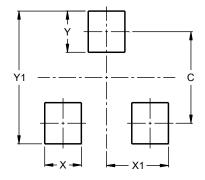


	SOT23								
Dim	Min	Max	Тур						
Α	0.37	0.51	0.40						
В	1.20	1.40	1.30						
С	2.30	2.50	2.40						
D	0.89	1.03	0.915						
F	0.45	0.60	0.535						
G	1.78	2.05	1.83						
Н	2.80	3.00	2.90						
J	0.013	0.10	0.05						
K	0.890	1.00	0.975						
K1	0.903	1.10	1.025						
L	0.45	0.61	0.55						
L1	0.25	0.55	0.40						
М	0.085	0.150	0.110						
а	0°	8°							
All	All Dimensions in mm								

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23



Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Υ	0.9
Y1	2.9



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